**Amendments to the Claims**:

The listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims**:

Claim 1. (Currently Amended) An electronic device storing and protecting in a case member an insulating substrate and an electronic substrate having an electronic circuit composed of mounted parts, including at least one of ~~such as~~ conductors, resistors, and capacitors formed in a film form on said insulating substrate, wherein:

said ~~film form~~ conductors formed on said surface of said insulating substrate, excluding a probing portion for electrically connecting with said conductors in a manufacturing process of said electronic device and a mounting portion for connection ~~which is connections~~ of said conductors with said mounted parts, are overcoated with one of glass [[or]] and resin; [[,]] and

openings of said probing portion and said mounting portion which are not overcoated are all formed in a shape having no corners at an angle which is less than or equal to 90°; ~~or less, for example, in a~~

said openings have a shape selected from the group consisting of

circular, ~~shape, in an~~ elliptical, ~~shape, or in a shape that corners of~~ a tetragon [[are]] having rounded corners and a tetragon having ~~(R, circular arc) or~~ chamfered corners; ~~(C, tapered),~~ and

said openings surrounded by said overcoating materials are covered with solder or metallic paste.

Claim 2. (Currently Amended) An electronic device storing and protecting in a case member an insulating substrate and an electronic substrate having an electronic circuit composed of mounted parts such as conductors, resistors, and capacitors formed in a film form on said insulating substrate, wherein:

a majority portion of said film-form conductors formed on said surface of said insulating substrate are ~~mostly~~ overcoated with an overcoat material of glass or resin; ~~, and the remainder~~

a remaining portion is overcoated with a conductive member ~~such as~~ which is one of solder [[or]] and metallic paste; [[,]] and

[[the]] a surface of said majority portion that is overcoated ~~part by solder or metallic paste~~ is formed in a shape having no corners at an angle which is less than or equal to 90°; ~~or less, for example, in a~~

said surface of said majority portion has a shape selected from the group consisting of circular, ~~shape, in an~~ elliptical, ~~shape, or in a shape that corners of~~ a tetragon [[are]] having rounded corners, and a tetragon having ~~(R, circular arc) or~~ chamfered corners. ~~(C, tapered).~~

Claim 3. (Original) An electronic device according to Claim 1, wherein the shape of said overcoated part by solder or metallic paste is a tetragon having a ratio of the short side to the long side within the range from 0.5 to 1.5 or an ellipse.

Claim 4. (Original) An electronic device according to Claim 1, wherein the shape of said overcoated part by solder or metallic paste is a tetragon that said corners are rounded at R or C of 1/10 of the long side or more.

Claim 5. (Original) An electronic device according to Claim 1, wherein the shape of said overcoated part by solder or metallic paste is a tetragon that said corners are rounded at R or C between 0.1 and 0.5.

Claim 6. (Currently Amended) An electronic device storing and protecting in a case member an insulating substrate and an electronic substrate having an electronic circuit composed of mounted parts, including at least one of ~~such as~~ conductors, resistors, and capacitors formed in a film form on said insulating substrate, wherein:

said ~~film form~~ conductors formed on said surface of said insulating substrate, excluding a probing portion for electrically connecting with said conductors in a manufacturing process of said electronic device and a mounting portion ~~which is connections~~ for connection of said conductors with said mounted parts, are overcoated with one of glass [[or]] and resin; and

said probing portion or said mounting portion is subject to a conductor pattern that said portion is formed in a position branched from a conductor line where the function of said electronic circuit is not damaged even if said portion is disconnected or said conductors are formed in parallel.

Claim 7. (Original) An electronic device according to Claim 6, wherein as means for forming said conductors in parallel, said conductors are formed in a multilayer on said substrate, and said probing portion or said mounting portion is formed in the uppermost layer, and said conductors in the lower layers are arranged in parallel with said portion.

Claim 8. (Currently Amended) An electronic device according to Claim 6, wherein:

~~said film form conductors formed on said surface of said insulating substrate excluding a probing portion for electrically connecting with said conductors in a manufacturing process of said electronic device and a mounting~~

~~portion which is connections of said conductors with said mounted parts are overcoated with glass or resin and~~

in one of said probing portion [[or]] and said mounting portion, [[the]] conductor width is wider than [[that]] a width of the other parts; and

[[the]] a width of unovercoated opening faces is no greater than 2/3 of said conductor width ~~or less~~.

Claim 9. (Original) An electronic device according to Claim 1, wherein said case member is a joint of a member having a conductive terminal for electrically connecting said electronic substrate positioned in said case to an outside of said case and a member such as a cover, and said joint is formed via an adhesive, fusing, or sealing material, thus an airtight case member is obtained.

Claim 10. (Original) An electronic device according to Claim 1, wherein said conductors are composed of a main component of silver or copper.

Claim 11. (Currently Amended) An electronic device according to Claim 1, wherein:

said insulating substrate is made of ~~ceramics, and~~ a ceramic material;

said conductors and said resistors are formed by thick film printing; [[, and]]

said coating is formed by thick film printing of glass; [[, and]]

said probing portion and said mounting portion are printed with solder; [[,]] and

after loading said mounting parts, said solder is heated and fused~~, that is, so-called reflowed~~.

Claim 12. (Original) An electronic device according to Claim 11, wherein the print film thickness of said solder is 5 times or more of said overcoated glass film thickness.

Claim 13. (Currently Amended) An electronic device according to Claim 11, wherein the print film thickness of said solder is at least 5 times ~~or more of~~ said print film thickness of said conductors.

Claim 14. (Currently Amended) An electronic device according to Claim 11, wherein said solder is composed of a main component comprising one of lead [[or]] and tin.

Claim 15. (Original) An electronic device according to Claim 1, wherein said device is a thermal type air flow measuring instrument.

Claim 16. (Original) An electronic device according to Claim 15, wherein said thermal type air flow measuring instrument measures a flow rate of intake air into a car engine and is attached to an intake air passage.

Claim 17. (Original) An electronic device according to Claim 15, wherein whole or part of said case member for storing and protecting said electronic substrate is positioned in a flow path of a fluid to be measured.